

## DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled TECHNIQUE FOR ELIMINATION OF PITTING ON SILICON SUBSTRATE DURING GATE STACK ETCH, the specification of which (check one):

- is attached hereto.  
 was filed on 07/16/96 as United States application serial no. 08/682,935 and was amended on \_\_\_\_\_.  
 was filed on \_\_\_\_\_ as PCT international application no. \_\_\_\_\_ and was amended under PCT Article 19 on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

| (number) | (country) | (day/month/year filed) | Priority Claimed<br>Yes | No |
|----------|-----------|------------------------|-------------------------|----|
|----------|-----------|------------------------|-------------------------|----|

| (number) | (country) | (day/month/year filed) | Priority Claimed<br>Yes | No |
|----------|-----------|------------------------|-------------------------|----|
|----------|-----------|------------------------|-------------------------|----|

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

|                          |               |   |
|--------------------------|---------------|---|
| (application serial no.) | (filing date) | (status - pending, patented or abandoned) |
|--------------------------|---------------|---|

|                          |               |   |
|--------------------------|---------------|---|
| (application serial no.) | (filing date) | (status - pending, patented or abandoned) |
|--------------------------|---------------|---|

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

|                               |               |
|-------------------------------|---------------|
| (provisional application no.) | (filing date) |
|-------------------------------|---------------|

|                               |               |
|-------------------------------|---------------|
| (provisional application no.) | (filing date) |
|-------------------------------|---------------|

|                               |               |
|-------------------------------|---------------|
| (provisional application no.) | (filing date) |
|-------------------------------|---------------|

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012  
 Laurence B. Bond, Reg. No. 30,549  
 Allen C. Turner, Reg. No. 33,041  
 Robert G. Winkle, Reg. No. 37,474  
 W. Bryan Farney, Reg. No. 32,651

William S. Britt, Reg. No. 20,969  
 Joseph A. Walkowski, Reg. No. 28,765  
 Alan K. Aldous, Reg. No. 31,905  
 Patrick McBride, Reg. No. 39,295  
 Michael L. Lynch, Reg. No. 30,871

Thomas J. Rossa, Reg. No. 26,799  
 James R. Duzan, Reg. No. 28,393  
 Julie K. Morris, Reg. No. 33,263  
 Edgar R. Cataxinos, Reg. No. 39,931  
 Lia M. Pappas, Reg. No. 34,095

Address all correspondence to:

Joseph A. Walkowski, telephone no. (801) 532-1922.  
**TRASK, BRITT & ROSSA**  
 P.O. BOX 2550  
 Salt Lake City, Utah 84110

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Pai-Hung Pan  
 Inventor's signature   
 Residence: Boise, Idaho  
 Citizenship: U.S.A.  
 Post Office Address: 2773 East Migratory Drive, Boise, Idaho 83706

Date 10-07-96

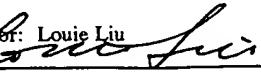
DECLARATION FOR PATENT APPLICATION  
(continuation page)

Invention title: TECHNIQUE FOR ELIMINATING PITTING ON SILICON SUBSTRATE DURING GATE STACK ETCH

Inventor name(s) appearing on first declaration page: Pai-Hung Pan

 Additional original, first and joint inventor(s):

Full name of second joint inventor: Louie Liu

Inventor's signature 

Date

10-01-96

Residence: Meridian, Idaho

Citizenship: Taiwan

Post Office Address: 1412 N. Sandlin Avenue, Meridian, Idaho 83642

Full name of third joint inventor: Ravi Iyer

Inventor's signature 

Date

10/02/96

Residence: Boise, Idaho

Citizenship: India

Post Office Address: 5600 S. Fuchsia, Boise, Idaho 83705

09/07/2002